

10-12-2001

Docket No.: SLA0547

FORM PTO-1595 (Modified)
(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)
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P08/REV02



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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

101871845

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Sheng Teng Hsu and Wei Pan

9-26-01
09965582

2. Name and address of receiving party(ies):

Name: Sharp Laboratories of America, Inc.

Internal Address: _____

Street Address: 5750 NW Pacific Rim Boulevard

City: Camas State: WA ZIP: 98607

Additional names(s) of conveying party(ies) ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: September 26, 2001

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: September 26, 2001

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Matthew D. Rabdau, Patent Attorney

Internal Address: Registration No. 43, 026

Sharp Laboratories of America, Inc.

Street Address: 5750 NW Pacific Rim Boulevard

10/11/2001 6T0N11 00000165 191457 09965582

01 FC:581 40.00 CH

City: Camas State: WA ZIP: 98607

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☒ Authorized to be charged to deposit account

8. Deposit account number:

19-1457

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Matthew D. Rabdau, Reg. No. 43,026

Name of Person Signing

Signature

September 26, 2001

Date

Total number of pages including cover sheet, attachments, and document: 4

PATENT

REEL: 12229 FRAME: 0428

ASSIGNMENT

WHEREAS, the undersigned Sheng Teng Hsu, a resident of Camas, WA, and Wei Pan, a resident of Vancouver, WA, (hereinafter termed "inventors") have invented certain new and useful improvements in:

METHOD OF FABRICATING COPPER INTERCONNECTS WITH VERY LOW-K INTER-LEVEL INSULATOR

and has executed a declaration or oath for an application for a United States patent disclosing and identifying the invention:

☒ Executed on the 26TH day of September, 2001;

or

☐ Having been previously filed and assigned
Serial Number / , and filing date ; and

WHEREAS Sharp Laboratories of America, Inc., a corporation of the State of Washington, (hereinafter termed "Assignee"), having a place of business at 5750 NW Pacific Rim Boulevard, Camas, State of Washington, wishes to acquire the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any and all countries of the world for patents, certificates of inventions or other government grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a

division, substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by said inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting application for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.
3. The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, said Inventors' heirs, legal representatives and assigns.
4. Said Inventor hereby warrants and represents that said Inventor has not Entered and will not enter into any assignment, contract, or understanding in conflict herein.

IN WITNESS WHEREOF, the said Inventors have executed this
Assignment on the date given below:

(1) Sheng Teng Hsu
Sheng Teng Hsu (Signature)

09/26/01
(Date)

(2) Wei Pan
Wei Pan (Signature)

9/26/01
(Date)
